

**APPENDIX D**

**Z (AXIAL) MEASUREMENT: CDMA 800 Channel 1013**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1013/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -7.89009 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -4, 363.7 mm

**Scans CH1013/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -4.59024 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 3, -1.4, 363.7 mm

**Point meas,TCoil on CH1013/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -5.94755 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 1, -1, 363.7 mm

**Point meas,TCoil on CH1013/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -48.6971 dB A/m  
 Location: 1, -1, 363.7 mm

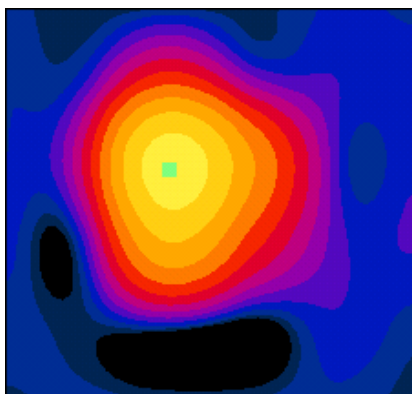
**Point meas,TCoil on CH1013/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

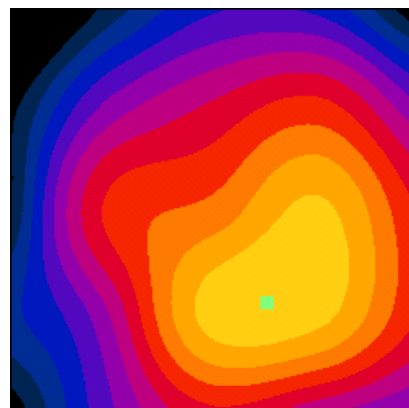
ABM1/ABM2 = 42.7495 dB  
 BWC Factor = -0.200998 dB  
 Location: 1, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16 scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 800 Channel 1013**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1013/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -12.659 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: -3.4, -5, 363.7 mm

**Point meas, TCoil on CH1013/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -12.1932 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**Point meas, TCoil on CH1013/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -56.6619 dB A/m  
 Location: -3, -5, 363.7 mm

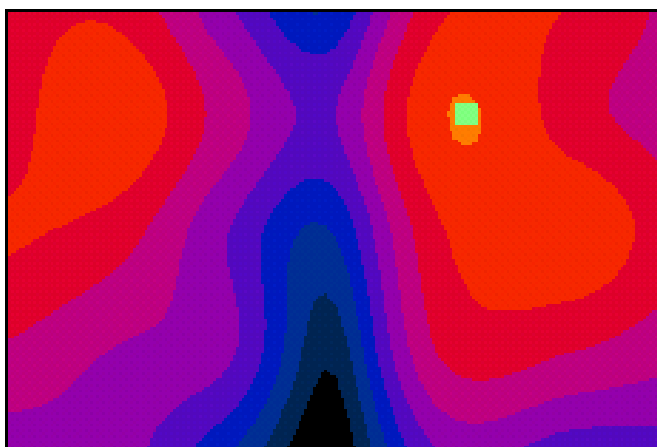
**Point meas, TCoil on CH1013/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 44.4687 dB  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 800 Channel 1013**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1013/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.8222 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 4.2, 3.8, 363.7 mm

**Point meas, TCoil on CH1013/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -14.3722 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -13, 363.7 mm

**Point meas, TCoil on CH1013/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -59.1265 dB A/m  
 Location: 5, -13, 363.7 mm

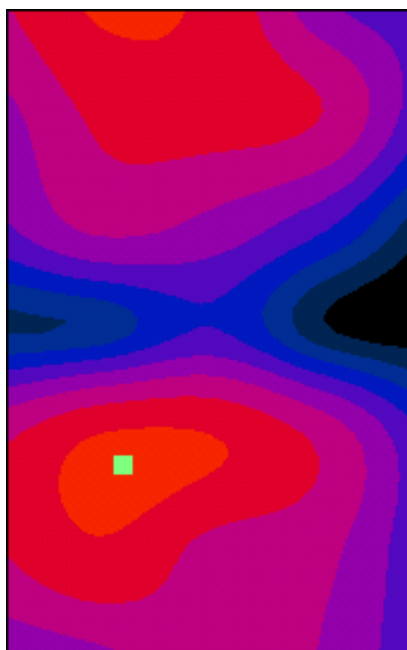
**Point meas, TCoil on CH1013/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 44.7542 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -13, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 800 Channel 383**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 836.49 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH383/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -8.57338 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -4, 363.7 mm

**Scans CH383/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -4.49114 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 3.4, -3, 363.7 mm

**Point meas,TCoil on CH383/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -5.6513 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 1, -1, 363.7 mm

**Point meas,TCoil on CH383/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -47.8855 dB A/m  
 Location: 1, -1, 363.7 mm

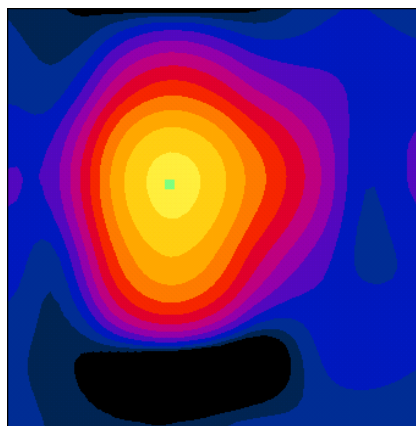
**Point meas,TCoil on CH383/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

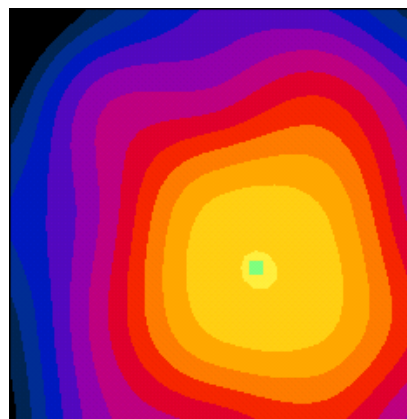
ABM1/ABM2 = 42.2342 dB  
 BWC Factor = -0.200998 dB  
 Location: 1, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 800 Channel 383**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087; Date: 1/24/2008**

Communication System: CDMA; Frequency: 836.49 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH383/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -12.29 dB A/m

BWC Factor = -0.200998 dB

Location: -3.8, -3, 363.7 mm

**Point meas,TCoil on CH383/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -12.4073 dB A/m

BWC Factor = -0.200998 dB

Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH383/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -56.3493 dB A/m

Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH383/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

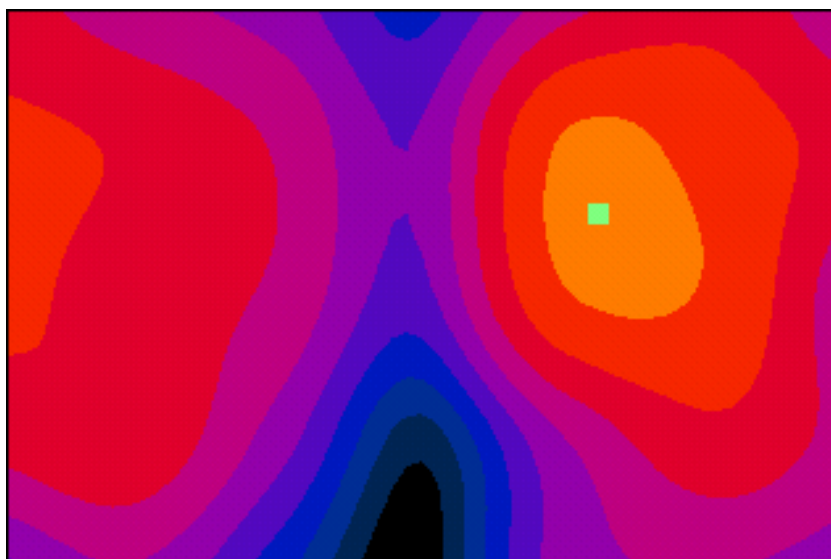
**Cursor:**

ABM1/ABM2 = 43.942 dB

BWC Factor = -0.200998 dB

Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 800 Channel 383**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 836.49 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH383/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -14.3659 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 1, 3.4, 363.7 mm

**Point meas,TCoil on CH383/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -16.7145 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 1, 3, 363.7 mm

**Point meas,TCoil on CH383/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -59.1482 dB A/m  
 Location: 1, 3, 363.7 mm

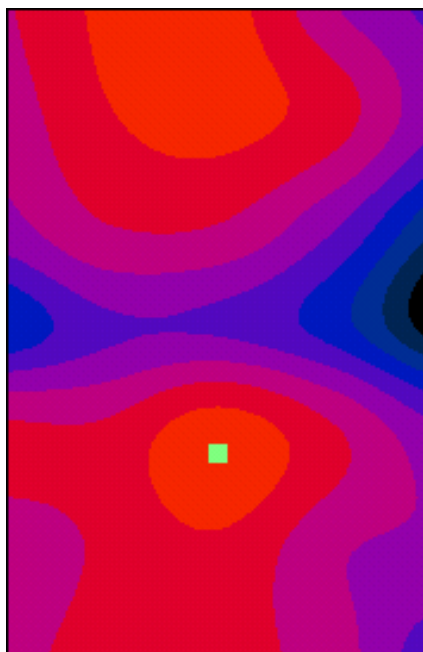
**Point meas,TCoil on CH383/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 42.4337 dB  
 BWC Factor = -0.200998 dB  
 Location: 1, 3, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 800 Channel 777**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH777/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -8.44502 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 4, -5, 363.7 mm

**Scans CH777/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.13942 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 3.4, -3, 363.7 mm

**Point meas, TCoil on CH777/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -46.6918 dB A/m  
 Location: 1, -1, 363.7 mm

**Point meas, TCoil on CH777/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -5.66806 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 1, -1, 363.7 mm

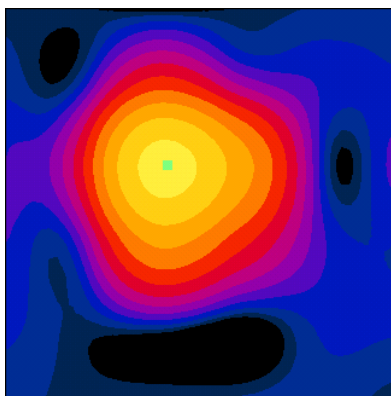
**Point meas, TCoil on CH777/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

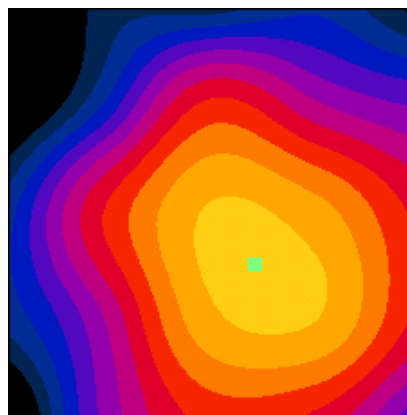
ABM1/ABM2 = 41.0237 dB  
 BWC Factor = -0.200998 dB  
 Location: 1, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m



**X RADIAL MEASUREMENT: CDMA 800 Channel 777**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087; Date: 1/24/2008**

Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH777/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -12.7525 dB A/m

BWC Factor = -0.200998 dB

Location: -6.2, -4.6, 363.7 mm

**Point meas,TCoil on CH777/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -15.9219 dB A/m

BWC Factor = -0.200998 dB

Location: -7, -5, 363.7 mm

**Point meas,TCoil on CH777/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -56.4471 dB A/m

Location: -7, -5, 363.7 mm

**Point meas,TCoil on CH777/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

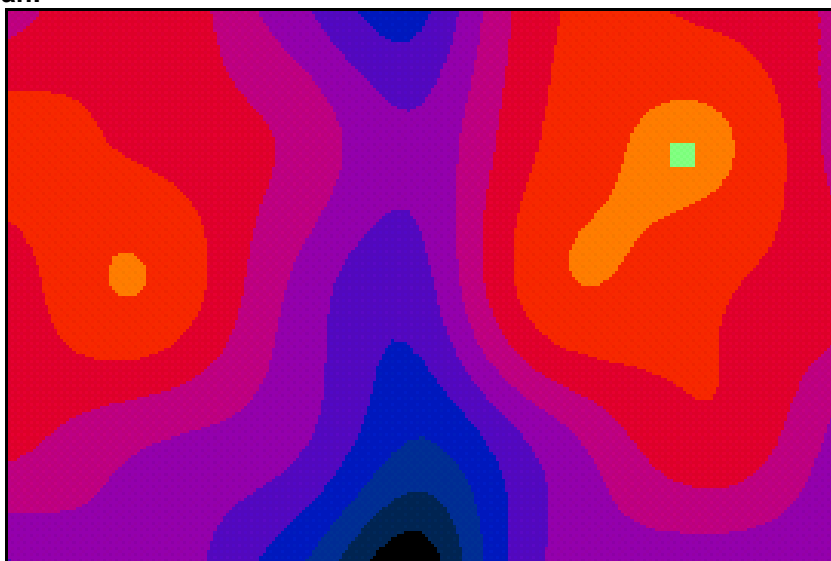
**Cursor:**

ABM1/ABM2 = 40.5253 dB

BWC Factor = -0.200998 dB

Location: -7, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m



**Y RADIAL MEASUREMENT: CDMA 800 Channel 777**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH777/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.7387 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 3.8, -9.4, 363.7 mm

**Point meas,TCoil on CH777/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -13.7911 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -9, 363.7 mm

**Point meas,TCoil on CH777/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -59.1218 dB A/m  
 Location: 5, -9, 363.7 mm

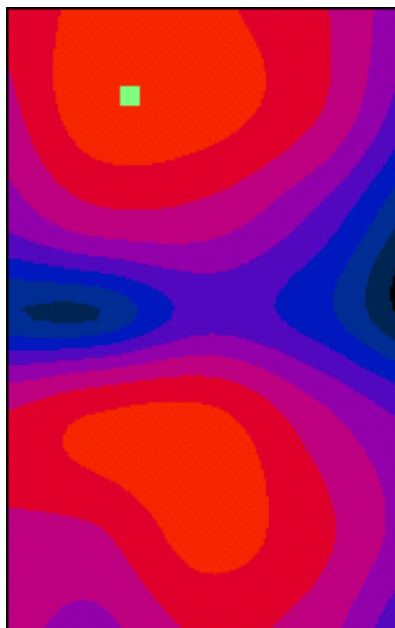
**Point meas,TCoil on CH777/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 45.3307 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -9, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 25**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1850 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -7.89752 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -4, 363.7 mm

**Scans CH25/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.6051 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -1, 363.7 mm

**Point meas, TCoil on CH25/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -9.03544 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -1, 363.7 mm

**Point meas, TCoil on CH25/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -52.0869 dB A/m  
 Location: 5, -1, 363.7 mm

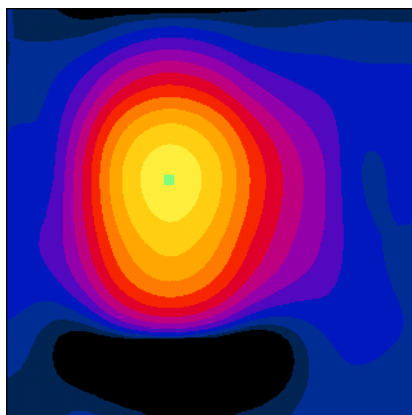
**Point meas, TCoil on CH25/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

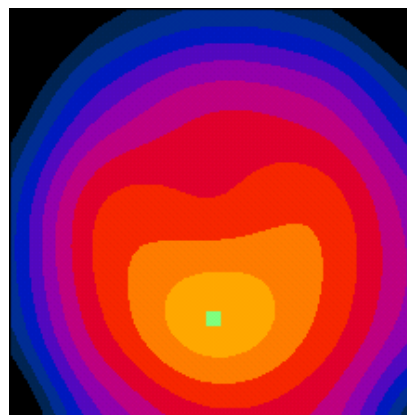
ABM1/ABM2 = 43.0515 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16 scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1900 Channel 25**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1850 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/x (longitudinal) 24 x 16/ABM**

**Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.3458 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

**x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -13.772 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**  
**x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -57.0614 dB A/m  
 Location: -3, -5, 363.7 mm

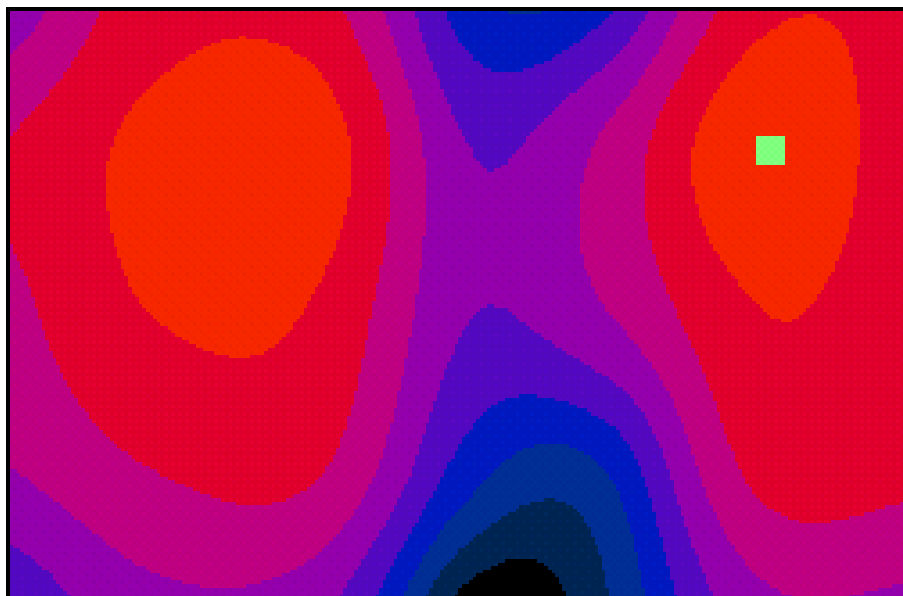
**Point meas,TCoil on CH25/x (longitudinal) at max**  
**x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 43.2895 dB  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1900 Channel 25**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1850 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -14.2499 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 2.6, -9.4, 363.7 mm

**Point meas, TCoil on CH25/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -14.394 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 1, -9, 363.7 mm

**Point meas, TCoil on CH25/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -59.4906 dB A/m  
 Location: 1, -9, 363.7 mm

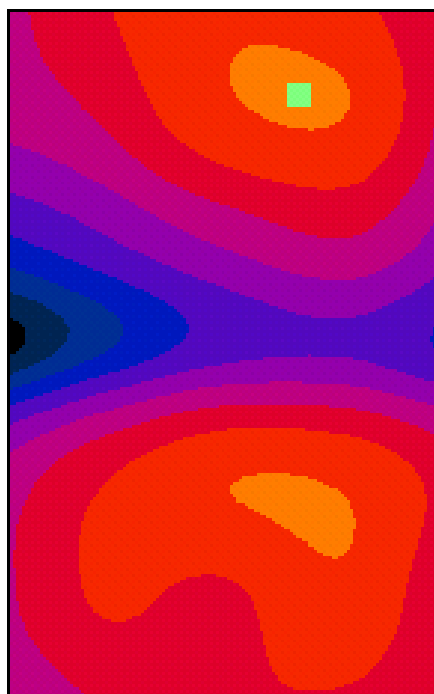
**Point meas, TCoil on CH25/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 45.0966 dB  
 BWC Factor = -0.200998 dB  
 Location: 1, -9, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 600**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/30/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH600/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.91225 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -5, 363.7 mm

**Scans CH600/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.68142 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 4.6, -5, 363.7 mm

**Point meas,TCoil on CH600/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -5.70202 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -5, 363.7 mm

**Point meas,TCoil on CH600/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -50.6736 dB A/m  
 Location: 5, -5, 363.7 mm

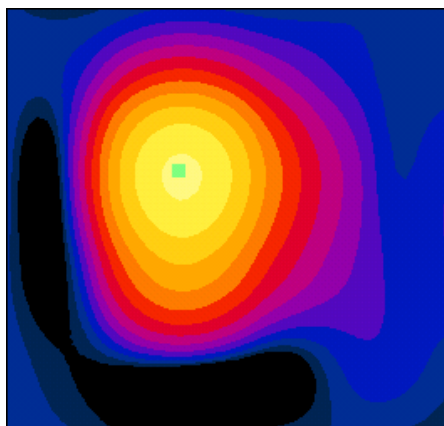
**Point meas,TCoil on CH600/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

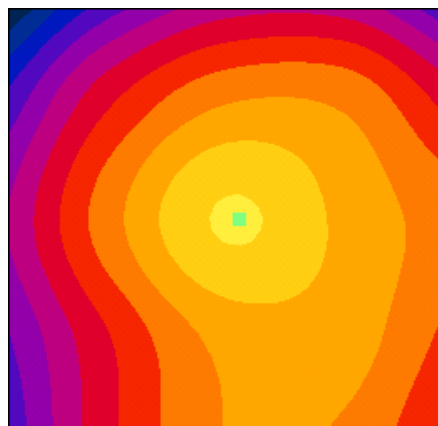
ABM1/ABM2 = 44.9716 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -5, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16 scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1900 Channel 600**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087; Date: 1/30/2008**

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH600/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.0893 dB A/m

BWC Factor = -0.200998 dB

Location: -7, -5, 363.7 mm

**Point meas, TCoil on CH600/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -13.4482 dB A/m

BWC Factor = -0.200998 dB

Location: -7, -5, 363.7 mm

**Point meas, TCoil on CH600/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -57.0113 dB A/m

Location: -7, -5, 363.7 mm

**Point meas, TCoil on CH600/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

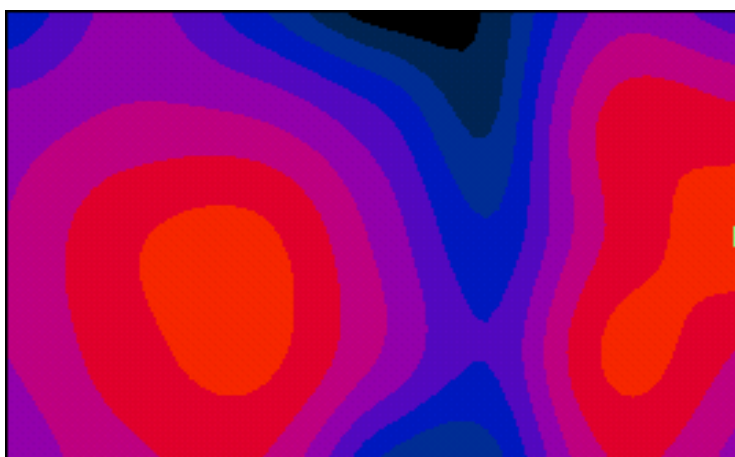
**Cursor:**

ABM1/ABM2 = 43.5631 dB

BWC Factor = -0.200998 dB

Location: -7, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1900 Channel 600**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/30/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH600/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.5651 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -9.4, 363.7 mm

**Point meas,TCoil on CH600/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -17.2306 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -9, 363.7 mm

**Point meas,TCoil on CH600/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -59.1835 dB A/m  
 Location: 5, -9, 363.7 mm

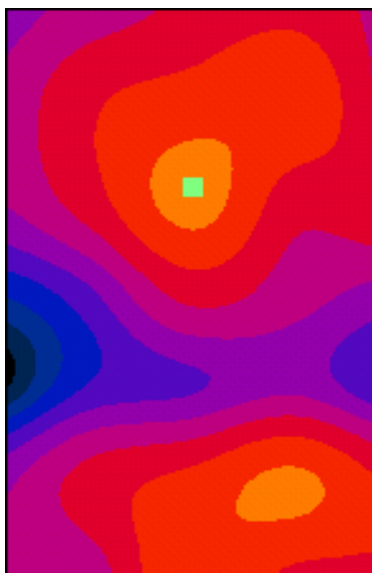
**Point meas,TCoil on CH600/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 41.9529 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -9, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m



**Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 1175**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087; Date: 1/24/2008**

Communication System: CDMA; Frequency: 1910 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1175/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.04506 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -5, 363.7 mm

**Scans CH1175/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.63419 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 4.6, -4.6, 363.7 mm

**Point meas, TCoil on CH1175/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -6.39832 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -5, 363.7 mm

**Point meas, TCoil on CH1175/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -51.3949 dB A/m  
 Location: 5, -5, 363.7 mm

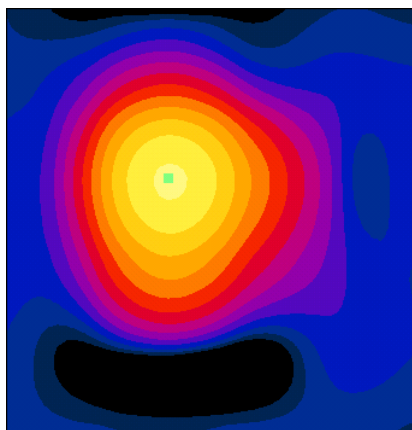
**Point meas, TCoil on CH1175/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

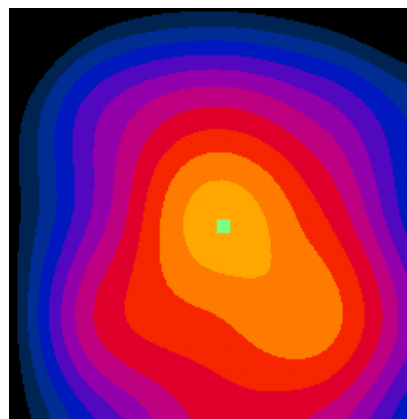
ABM1/ABM2 = 44.9966 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -5, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16 scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1900 Channel 1175**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1910 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1175/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -12.9248 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: -3.8, -3, 363.7 mm

**Point meas, TCoil on CH1175/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -13.6546 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**Point meas, TCoil on CH1175/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -56.9477 dB A/m  
 Location: -3, -5, 363.7 mm

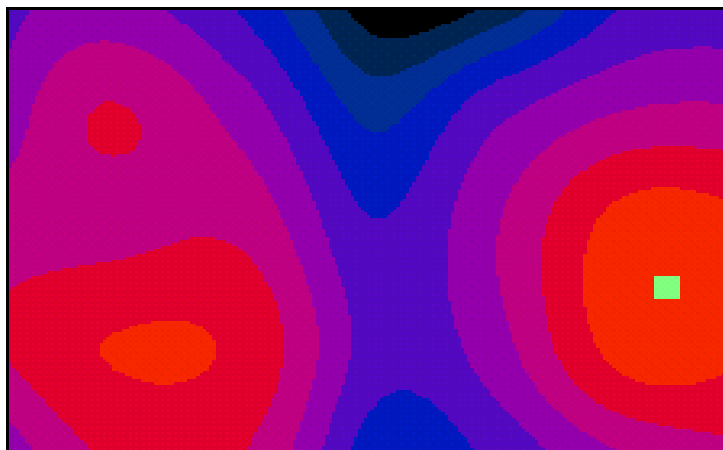
**Point meas, TCoil on CH1175/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 43.2931 dB  
 BWC Factor = -0.200998 dB  
 Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1900 Channel 1175**

**Equipment Setting:**

**DUT: S4000; Type: Cellular Phone ; Serial Number: 1087;**  
 Communication System: CDMA; Frequency: 1910 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 1/24/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/19/2007
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE3 Sn494; Calibrated: 3/14/2007
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1175/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -14.1967 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 4.2, -9.8, 363.7 mm

**Point meas, TCoil on CH1175/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -14.3251 dB A/m  
 BWC Factor = -0.200998 dB  
 Location: 5, -9, 363.7 mm

**Point meas, TCoil on CH1175/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -59.3301 dB A/m  
 Location: 5, -9, 363.7 mm

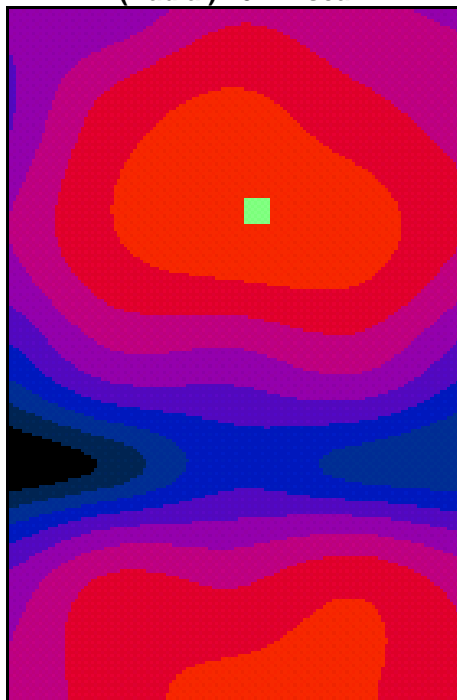
**Point meas, TCoil on CH1175/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 45.005 dB  
 BWC Factor = -0.200998 dB  
 Location: 5, -9, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m